



REV	MODIFICATION	DATE	DRAW
B	EN-04-0419	04.14.04"	Aaron
C	EN-04-0505	05.12.04"	Aaron
D	EN-04-0717	07.16.04"	Aaron

- NOTES:
- Material :
Housing : Thermoplastic UL94V-0
Contact : BERYLLIUM C17200R-H,T=0.10mm.
 - Plating :
Contact Plating - Gold over 45u" MIN.Nickel
Solder Tail Plating - Gold Flash over 45u" MIN.Nickel
 - Contact Forces :
Max. 0.5 N For 0.5mm Contact Deflection.
Min. 0.25 N For 0.5mm Contact Deflection.
 - Order Information :
SIMMP-006XXBXX1
30 : GOLD PLATING 30u"
0 : TAPE REEL
1 : TUBE
0 : TIN/LEAD PLATING
T : LEAD FREE

DIMENSION IN mm [Inch]		PROD. SPEC.	ALMITA CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		SP0052	Subscriber Identify Module Card	
.X±0.30	.X"± 1'	PKG. SPEC.	TITLE	CUSTOMER DRAWING
.XX±0.20	.X"± 0.5'	PPP-SIM-005	Simple Style Conn. 6 Pin	
.XXX±0.10	.XX"± 0.25'	APPROVE	FILE NO. KFP-052	DWG NO. SIMMP-006XXBXX1
		CHECK	SIZE A4	PROJ. SHEET 1 / 1
		DRAW	SCALE 4:1	REV D